

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02	100.0	0.18
			<b>Subtotal</b>	<b>0.02</b>	<b>100</b>	<b>0.18</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.2	100.0	1.5
			<b>Subtotal</b>	<b>0.2</b>	<b>100</b>	<b>1.5</b>
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	60.05	100.0	454.5
			<b>Subtotal</b>	<b>60.05</b>	<b>100</b>	<b>454.5</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.03	100.0	7.83
			<b>Subtotal</b>	<b>1.03</b>	<b>100</b>	<b>7.83</b>
Mould Compound	polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.61	1.6	4.65
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.5	6.5	18.91
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5	13.0	37.82
	Filler	Silica fused	60676-86-0	29.98	78.0	226.9
	Carbon Black	Carbon black	1333-86-4	0.27	0.7	2.04
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.08	0.2	0.58
			<b>Subtotal</b>	<b>38.44</b>	<b>100</b>	<b>290.9</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.06	100.0	0.47
			<b>Subtotal</b>	<b>0.06</b>	<b>100</b>	<b>0.47</b>
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.01	5.0	0.08
	Pure metal	Silver (Ag)	7440-22-4	0	1.5	0.02
	Pure metal	Lead (Pb)	7439-92-1	0.19	93.5	1.42
			<b>Subtotal</b>	<b>0.2</b>	<b>100</b>	<b>1.52</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>756.9</b>

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